

ABSTRACT OF THE DISCLOSURE (FIGS. 1, 26)

"SEMICONDUCTOR DEVICE"

A thin film passive element includes at least one of a capacitance element having a plurality of
5 conductive layers and a dielectric material layer and an inductance element formed of a patterned conductive layer is stacked on a circuit element-forming region of a semiconductor substrate provided with a plurality of connection pads and is connected to the circuit element
10 of the circuit element-forming region.